

OUR POWERFUL FAMILY OF WAFER-LEVEL BURN-IN SYSTEMS FOR DIGITAL & ANALOG APPLICATIONS

From Complex Digital Devices to SiC/GaN and photonics, our wafer-level burn-in solutions are purpose-built to tackle tomorrow's toughest challenges. Backed by a proven system family, they deliver dependable performance across demanding applications.

Enhanced with next-generation MEMS probe technology, our systems offer faster test speeds, higher current capacity and longer probe lifespan.

With modular scalability, advanced thermal control, and high-throughput architecture, our platforms support every stage of your product lifecycle – from fast-paced R&D to full-scale production.



**UP TO 16,000 POWER
SOURCES PER WAFER**

**7KW+ POWER DISSIPATION PER
WAFER WITH TIGHT THERMAL
REGULATION**

**CUTTING-EDGE
AUTOMATION FOR
SCALABLE
THROUGHPUT**

**ENGINEERED FOR WHAT'S NEXT
VERSATILE BY DESIGN.**